



9N95

Power MOSFET

9A, 950V N-CHANNEL POWER MOSFET

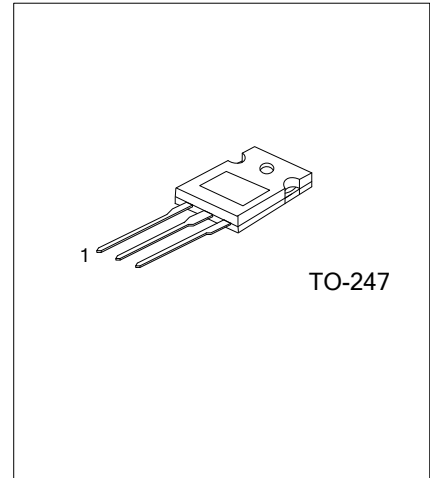
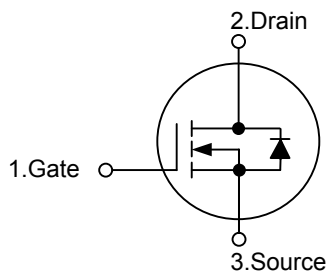
DESCRIPTION

The UTC **9N95** uses UTC's advanced proprietary, planar stripe, DMOS technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with low gate voltages. This device is suitable for use as a load switch or in PWM applications.

FEATURES

- * $R_{DS(ON)} = 1.4\Omega$ @ $V_{GS} = 10V$
- * Ultra Low Gate Charge (Typical 45 nC)
- * Low Reverse Transfer Capacitance ($C_{RSS} =$ Typical 14 pF)
- * Fast Switching Capability
- * Avalanche Energy Specified
- * Improved dv/dt Capability, High Ruggedness

SYMBOL



ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
9N95L-T47-T	9N95G-T47-T	TO-247	G	D	S	Tube

9N95L-T47-T (1)Packing Type (2)Package Type (3)Lead Free		(1) T: Tube (2) T47: TO-2475 (3) G: Halogen Free, L: Lead Free
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■ **ABSOLUTE MAXIMUM RATING** ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V _{DSS}	950	V
Gate-Source Voltage		V _{GSS}	±30	V
Continuous Drain Current (T _C = 25°C)		I _D	9.0	A
Pulsed Drain Current (Note 2)		I _{DM}	36	A
Avalanche Current (Note 2)		I _{AR}	9.0	A
Avalanche Energy	Single Pulsed(Note 3)	E _{AS}	900	mJ
	Repetitive(Note 2)	E _{AR}	28	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.0	V/ns
Power Dissipation		P _D	160	W
Linear Derating Factor above T _C = 25°C			1.28	W/°C
Junction Temperature		T _J	150	°C
Storage Temperature		T _{STG}	-55 ~ +150	°C

Note: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating : Pulse width limited by maximum junction temperature

3. $L = 21\text{mH}$, $I_{AS} = 9.0\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\ \Omega$, Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 9.0\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ **THERMAL DATA**

PARAMETER	SYMBOL	RATINGS	UNIT
Junction to Ambient	θ_{JA}	50	$^\circ\text{C}/\text{W}$
Junction to Case	θ_{JC}	0.78	$^\circ\text{C}/\text{W}$

■ **ELECTRICAL CHARACTERISTICS** ($T_J = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} = 0 V, I _D = 250μA	950			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} = 950 V, V _{GS} = 0 V			10	μA
Gate-Body Leakage Current	Forward	I _{GSSF}	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
	Reverse	I _{GSSR}	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
Breakdown Voltage Temperature Coefficient		ΔBV _{DSS} /ΔT _J	I _D =250μA, Referenced to 25°C		0.99		V/°C
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} = V _{GS} , I _D = 250μA	3.0		5.0	V
Static Drain-Source On-Resistance		R _{DS(ON)}	V _{GS} = 10V, I _D = 4.5A		1.05	1.4	Ω
DYNAMIC PARAMETERS							
Input Capacitance		C _{ISS}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz		2100	2730	pF
Output Capacitance		C _{OSS}			175	230	pF
Reverse Transfer Capacitance		C _{RSS}			14	18	pF
SWITCHING CHARACTERISTICS							
Turn-On Delay Time		t _{D(ON)}	V _{DD} = 475V, I _D =11.0 A, R _G = 25Ω (Note 1, 2)		50	110	ns
Turn-On Rise Time		t _R			120	250	ns
Turn-Off Delay Time		t _{D(OFF)}			100	210	ns
Turn-Off Fall Time		t _F			75	160	ns
Total Gate Charge		Q _G	V _{DS} = 760V, I _D = 11.0A, V _{GS} = 10 V (Note 1,2)		45	58	nC
Gate-Source Charge		Q _{GS}			13		nC
Gate-Drain Charge		Q _{GD}			18		nC

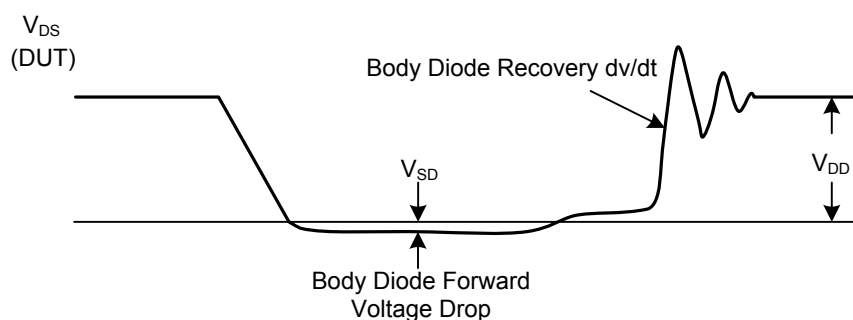
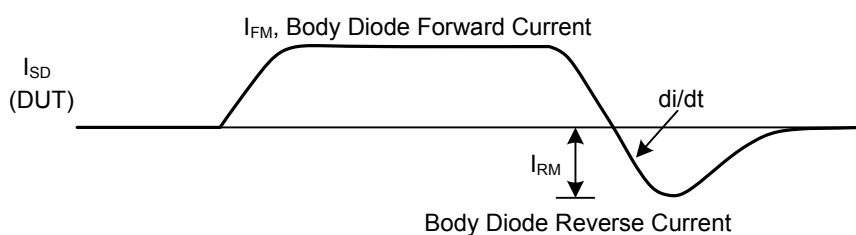
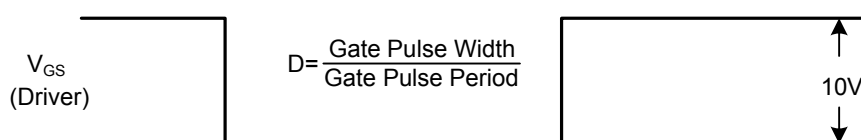
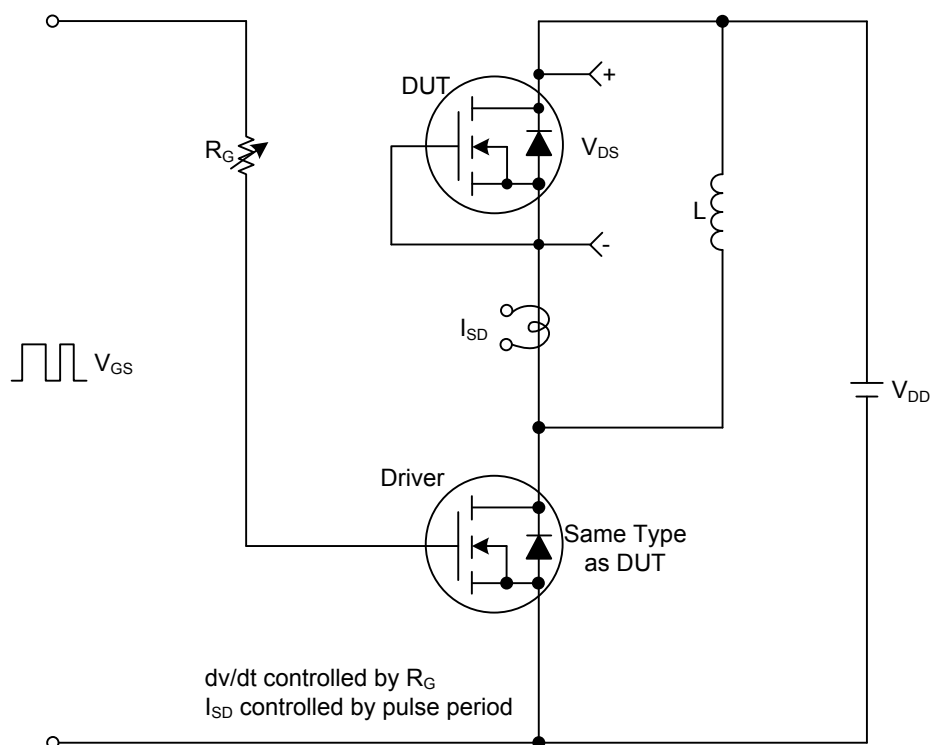
■ ELECTRICAL CHARACTERISTICS(Cont.)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_S = 9.0\text{ A}$			1.4	V
Maximum Continuous Drain-Source Diode Forward Current	I_S				9.0	A
Maximum Pulsed Drain-Source Diode Forward Current	I_{SM}				36	A
Reverse Recovery Time	t_{rr}	$V_{GS} = 0\text{ V}, I_S = 9.0\text{ A},$		550		ns
Reverse Recovery Charge	Q_{RR}	$dI_F / dt = 100\text{ A}/\mu\text{s}$ (Note 1)		6.5		μC

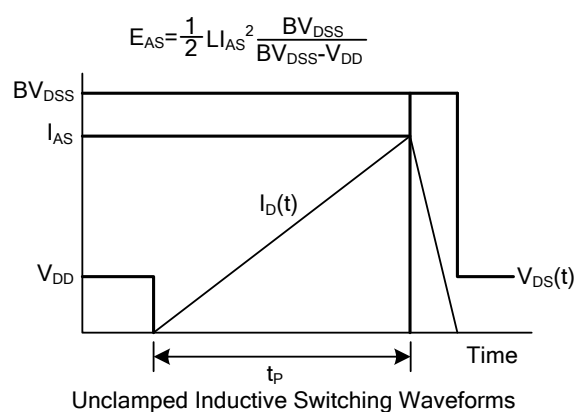
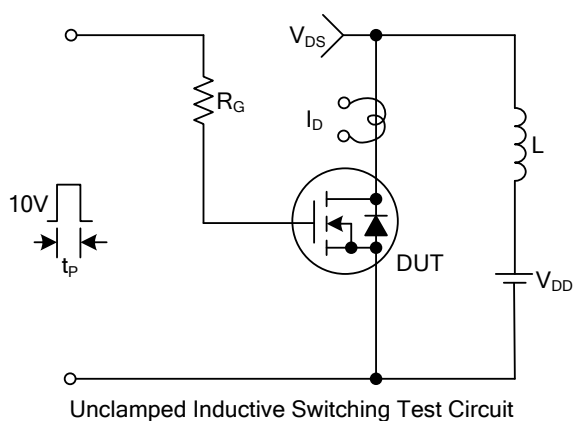
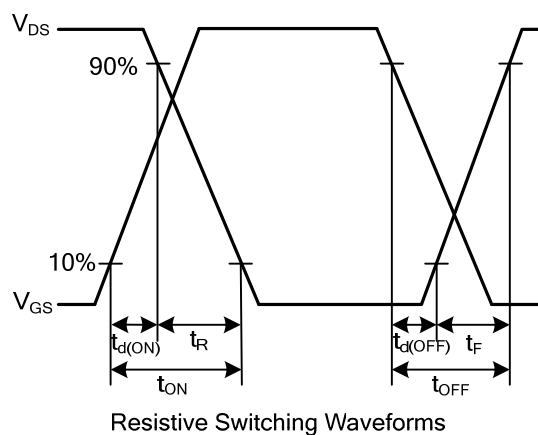
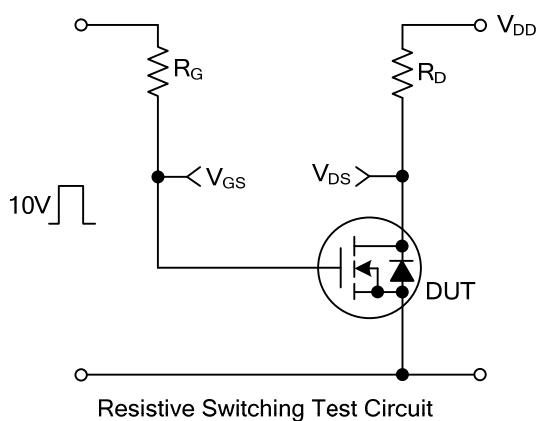
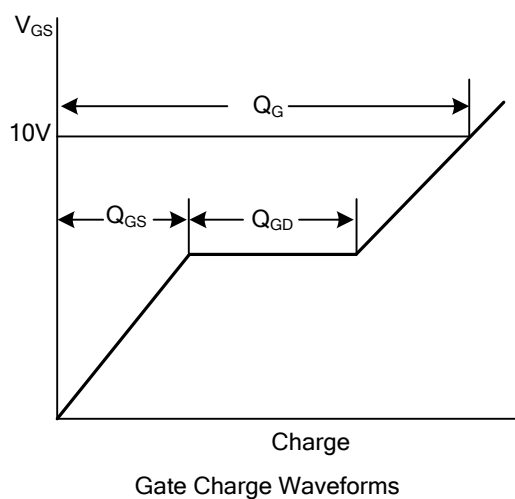
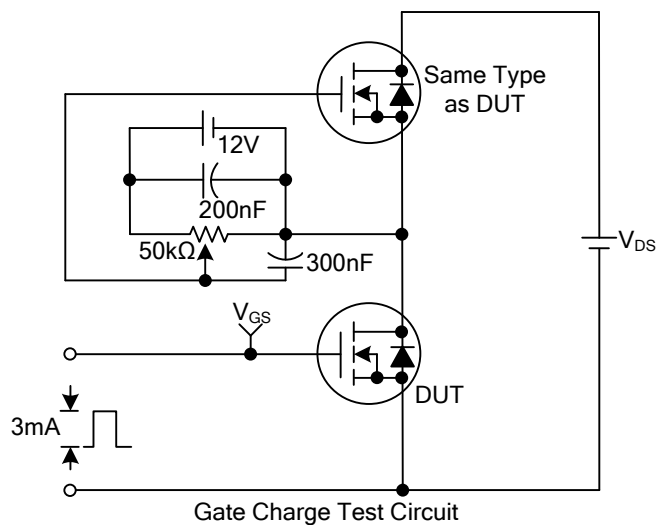
Notes: 1. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$

2. Essentially independent of operating temperature

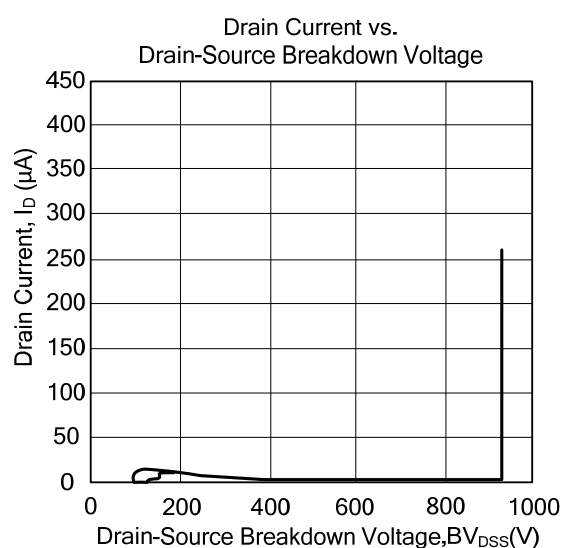
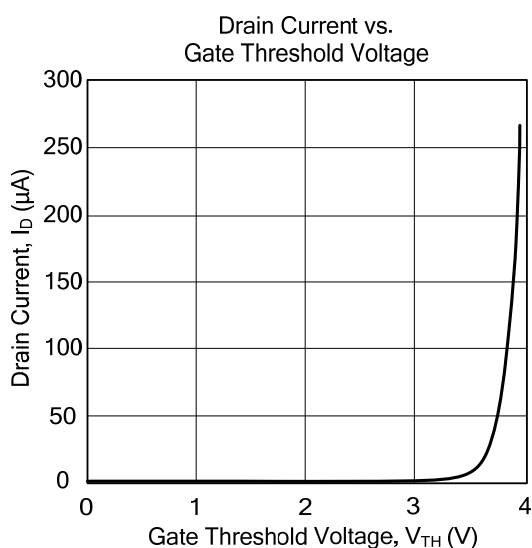
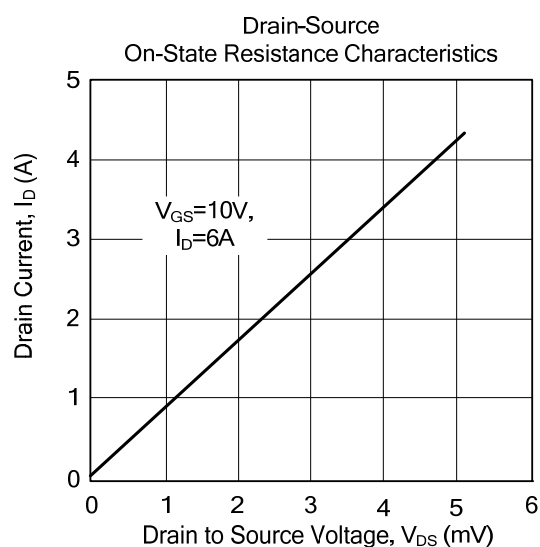
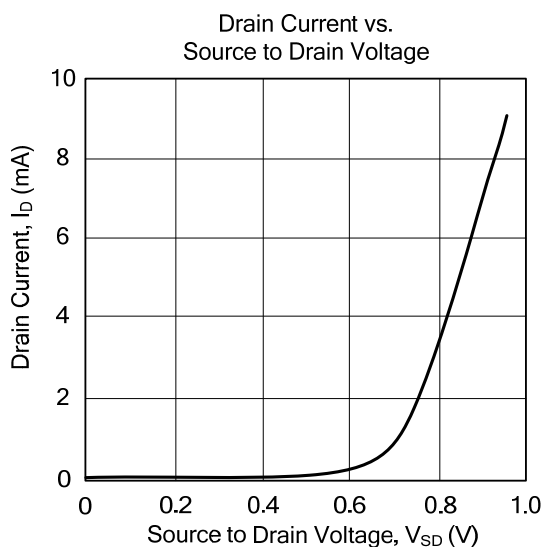
■ TEST CIRCUITS AND WAVEFORMS

Peak Diode Recovery dv/dt Test Circuit & Waveforms

■ TEST CIRCUITS AND WAVEFORMS(Cont.)



■ TYPICAL CHARACTERISTICS



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